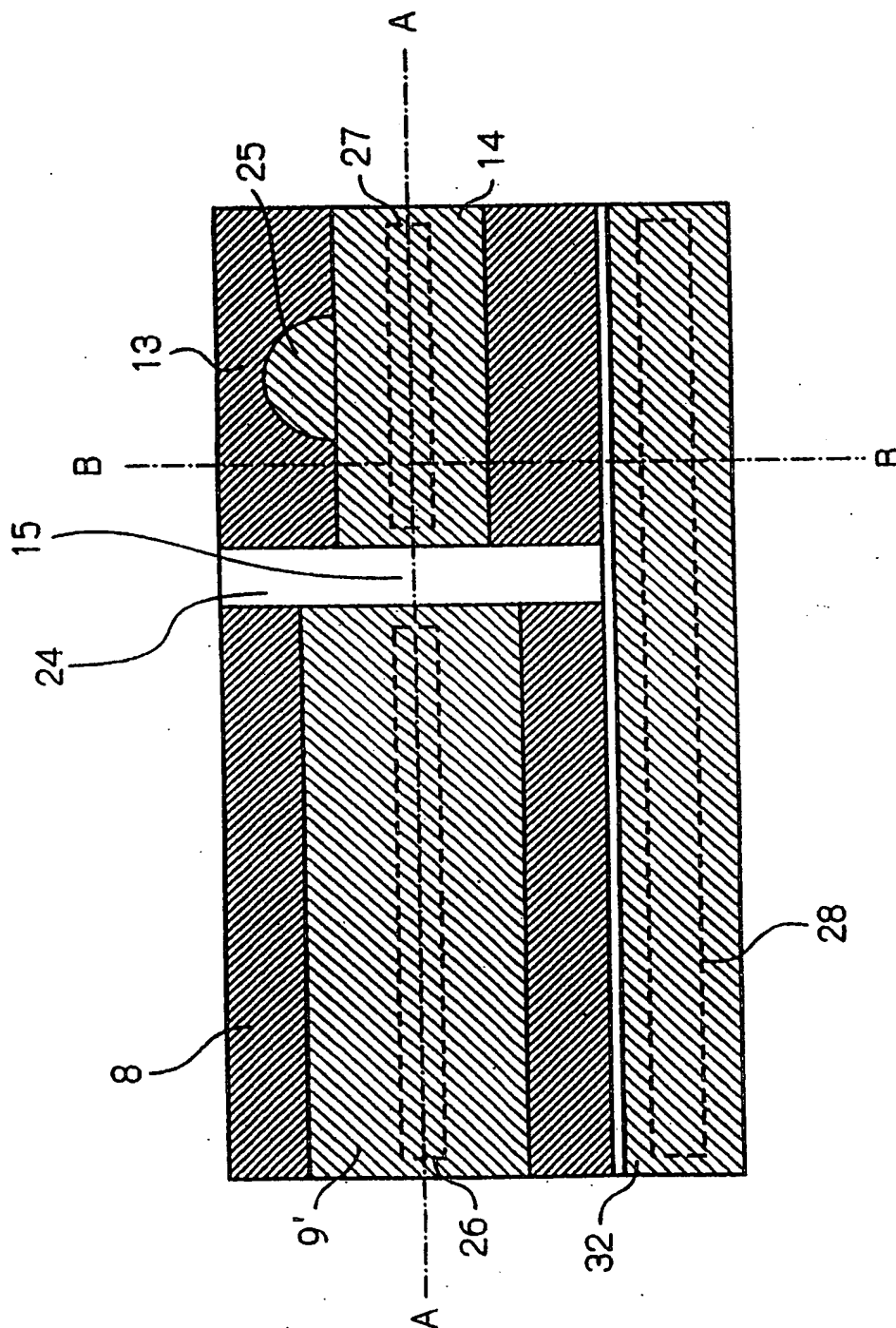


This diagram shows a cross-sectional view of a multi-layered electronic device assembly. The assembly consists of several stacked layers and internal components. From top to bottom, the layers are labeled 11, 13, 14, 15, 24, 9, 8, 7, 5, 16, 31, and 32. A central vertical strip is labeled 6. A wavy line representing a conductive or insulating interface is labeled 3. A horizontal line within the central strip is labeled 18. A small rectangular feature on the left side is labeled 17. A small rectangular feature on the right side is labeled 4. A small rectangular feature at the bottom center is labeled 5. A small rectangular feature at the bottom left is labeled 24. A small rectangular feature at the bottom right is labeled 24. A small rectangular feature at the bottom center is labeled 16. A small rectangular feature at the bottom center is labeled 31. A small rectangular feature at the bottom center is labeled 32.

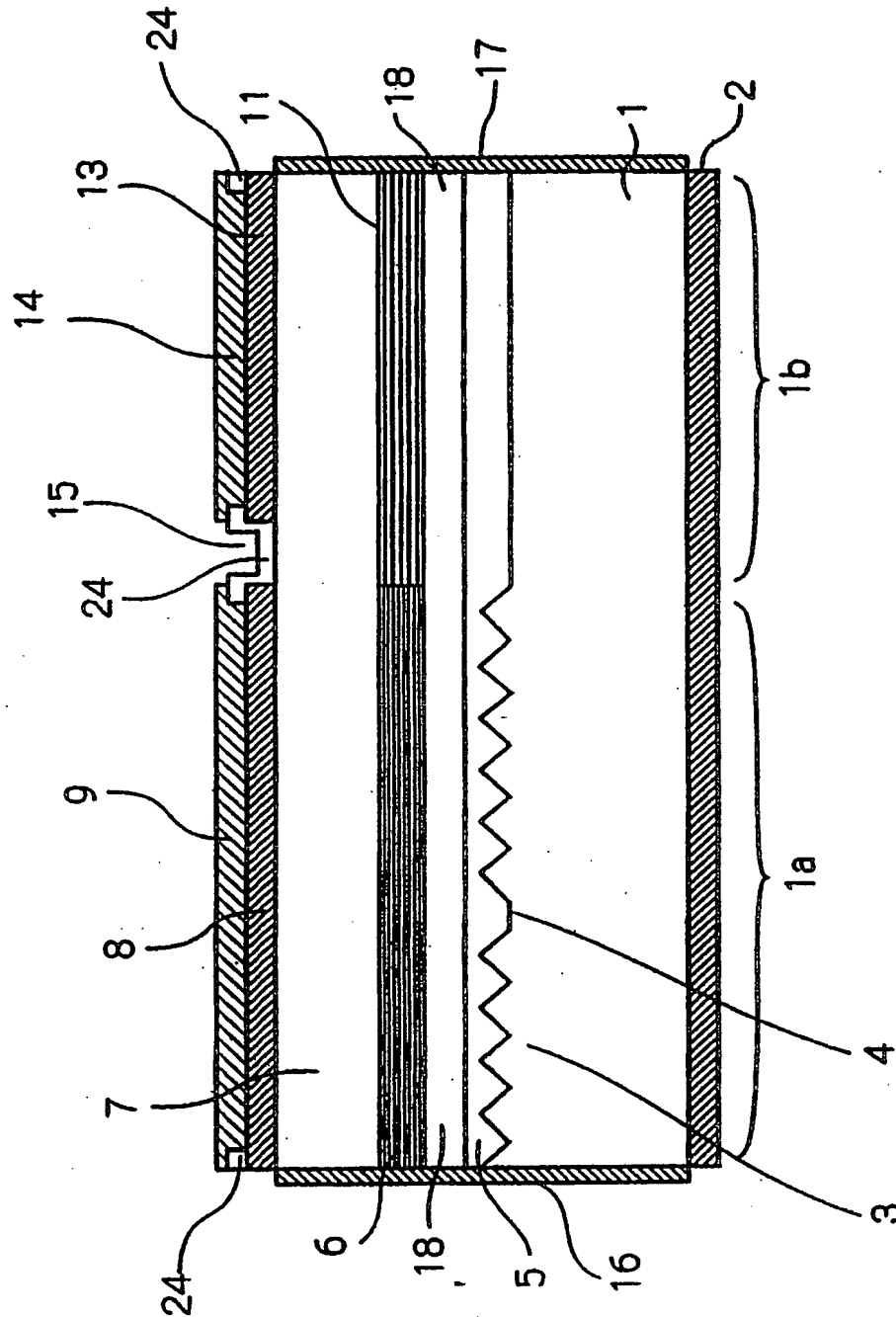
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[Fig. 2A]



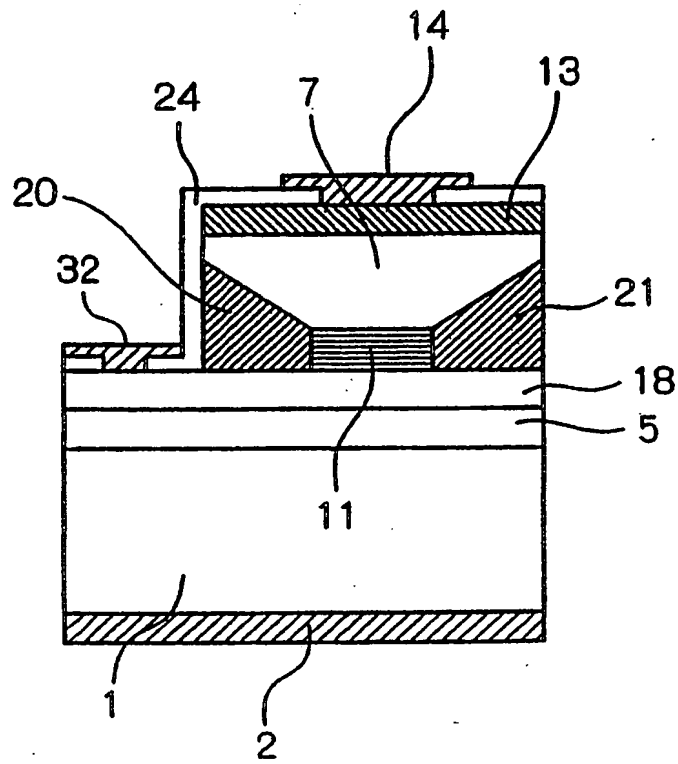
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[Fig. 2B]

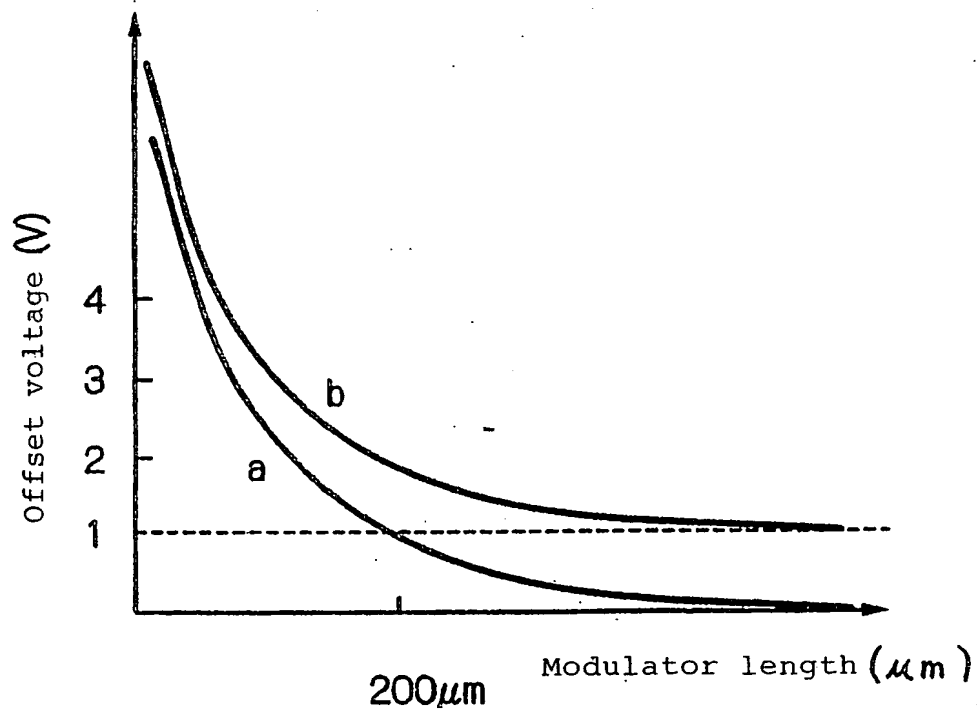


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[Fig. 2C]

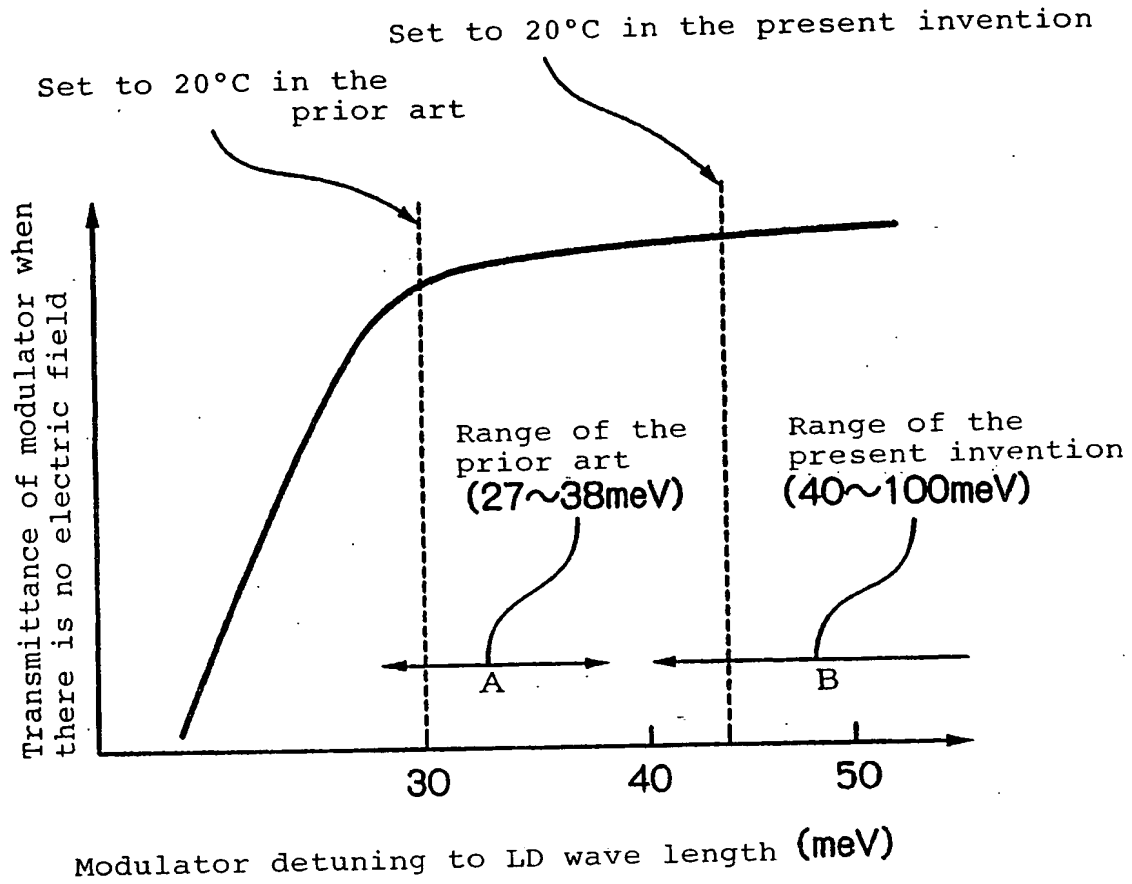


[Fig. 3]

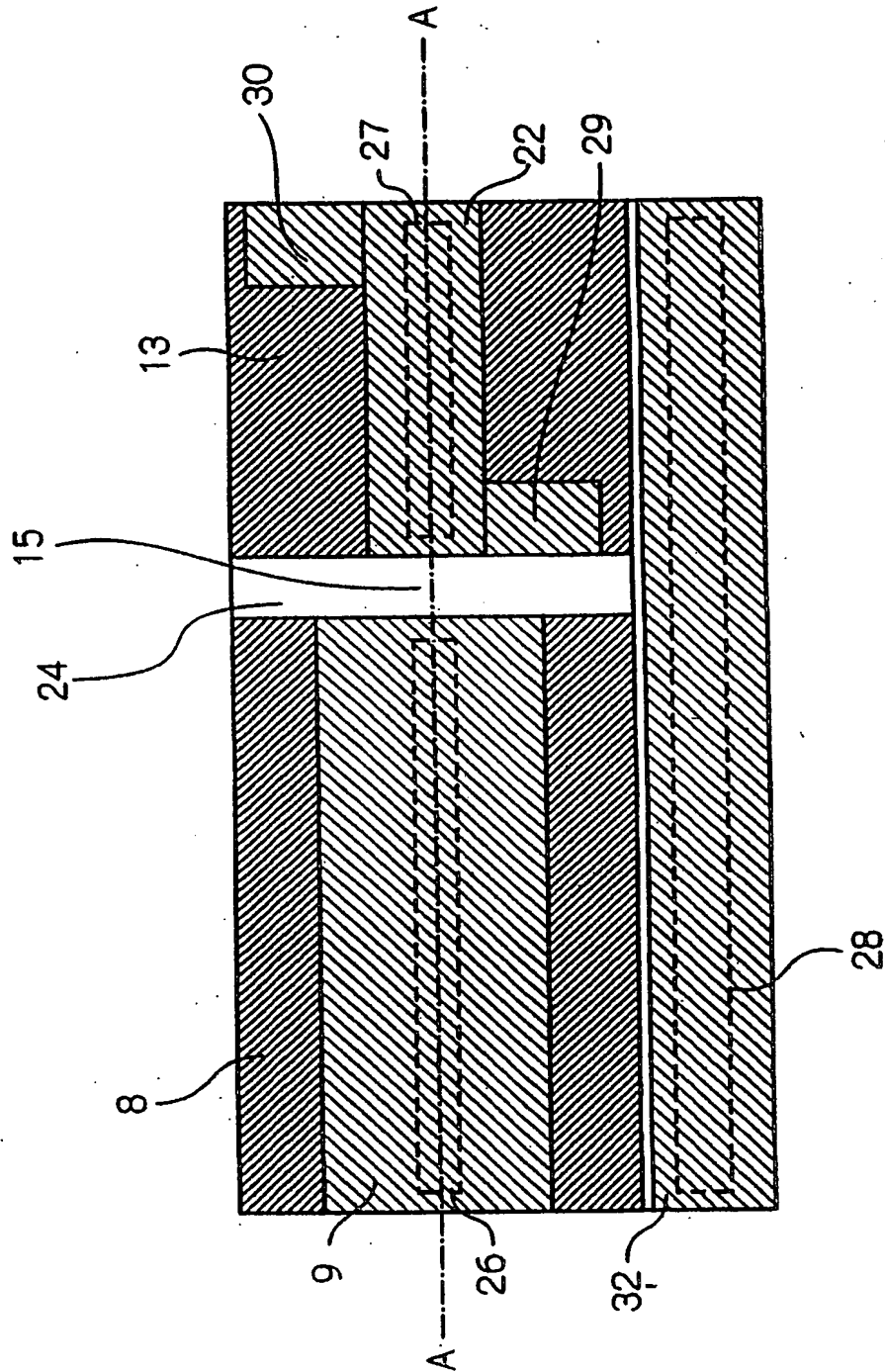


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[Fig.4]



[Fig. 5A]





[Fig. 6]

